

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT3008ITS8-1.8#TRPBF		(Engineering Calculation)			TSOT-23			
(printed on: 7/26/2011 6:12:01 AM)					TOTAL MASS (g):	0.01240669		
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT		
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000429	1000000	34578.12		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.004582	975000	369316.9		
		Iron (Fe)	7439-89-6	0.000113	24000	9107.989		
		Phosphorus (P)	7723-14-0	1.00E-06	300	80.60168		
		Zinc (Zn)	7440-66-6	3.00E-06	700	241.805		
		Nickel (Ni)	7440-02-0	0	0	0		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead Frame Total:				0.004699	1000000	378747.3
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.00066269	1000000	53413.92		
		External Plating Total:				0.00066269	1000000	53413.92
		Inter. Plating Ni	7440-02-0	0	0	0		
		Inter. Plating Ag	7440-22-4	8.00E-05	1000000	6448.134		
		Internal Plating Total:				8.00E-05	1000000	6448.134
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000351	750000	28291.19		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead (Pb)	7439-92-1	0	0	0		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Antimony (Sb)	7440-36-0	0	0	0		
		Resin (EP)		0.000117	250000	9430.396		
Die Attach Total:				0.000468	1000000	37721.59		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000777	130000	62627.5		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.004963	830000	400026.1		
		Antimony	1309-64-4	0	0	0		
		Trioxide (Sb2O3)						
		Metal Hydroxid		0.000209	35000	16845.75		
		Carbon Black (C)	1333-86-4	3.00E-05	5000	2418.05		
Encapsulation Total:				0.005979	1000000	481917.4		
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	8.90E-05	1000000	7173.549		
Estimated								
TOTAL MASS (g):						0.01240669		